



MSBS Material Safety Data Sheet

No.	Material Content Declaration					
	Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
1	Lead wire 38.43%	Copper (Cu)	7440-50-8	82.6000	99.9775	384,195.2
		Phosphorus (P)	7723-14-0	0.0008	0.0010	3.9
		Arsenic (As)	7440-38-2	0.0008	0.0010	3.9
		Tin (Sn)	7440-31-5	0.0008	0.0010	3.9
		Oxygen (O)	7782-44-7	0.0004	0.0005	1.9
		Sulfur (S)	7704-34-9	0.0110	0.0132	51.2
		Iron (Fe)	7439-89-6	0.0058	0.0007	26.9
		Nickel (Ni)	7440-02-0	0.0002	0.0003	1.2
		Bismuth (Bi)	7440-69-9	0.0017	0.0020	7.7
		Antimony (Sb)	1309-64-4	0.0017	0.0020	7.7
		Lead (Pb)	7439-92-1	0.0004	0.0005	1.9
		Zinc (Zn)	7440-66-6	0.0002	0.0003	1.2
		Total			82.62	
2	Solder wafer 3.27%	Lead (Pb)	7439-92-1	6.503	92.50	30,247.2
		Tin (Sn)	7440-31-5	0.352	5.00	1,637.2
		Silver (Ag)	7440-22-4	0.176	2.50	818.6
		Total			7.03	
3	Chip 2.36%	Silicon (Si)	7440-21-3	5.07	100.00	23,582.0
		Total			5.07	
4	Molding 55.68%	Silica (SiO ₂)	14808-60-7	88.72	74.11	412,661.0
		Epoxy resin	29690-82-2	20.35	17.00	94,653.4
		Phenolic resin	9003-35-4	10.53	8.80	48,977.9
		Phosphorus(P)	7723-14-0	0.06	0.05	279.1
		Carbon Black	1333-86-4	0.05	0.04	232.6
Total			119.71			
5	Plating 0.26%	Tin (Sn)	7440-31-5	0.56	100.00	2,604.7
		Total			0.56	
		Total mass (mg)		214.99		